

SOT1436-1

plastic, thermal enhanced super thin small outline package;
no leads; 10 terminals; 0.35 mm pitch, 2.0 mm x 1.7 mm x 0.3
mm body

6 June 2018

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	HX2SON
Package type industry code	HX2SON10
Package style descriptive code	HXSON (thermal enhanced extremely thin small outline; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	21-5-2015
Manufacturer package code	SOT1436

Table 1. Package summary

Parameter		Min	Nom	Max	Unit
package length		1.65	1.7	1.75	mm
package width		1.95	2	2.05	mm
seated height		0.28	0.3	0.33	mm
nominal pitch		-	0.35	-	mm
actual quantity of termination		-	10	-	A/A



2. Package outline

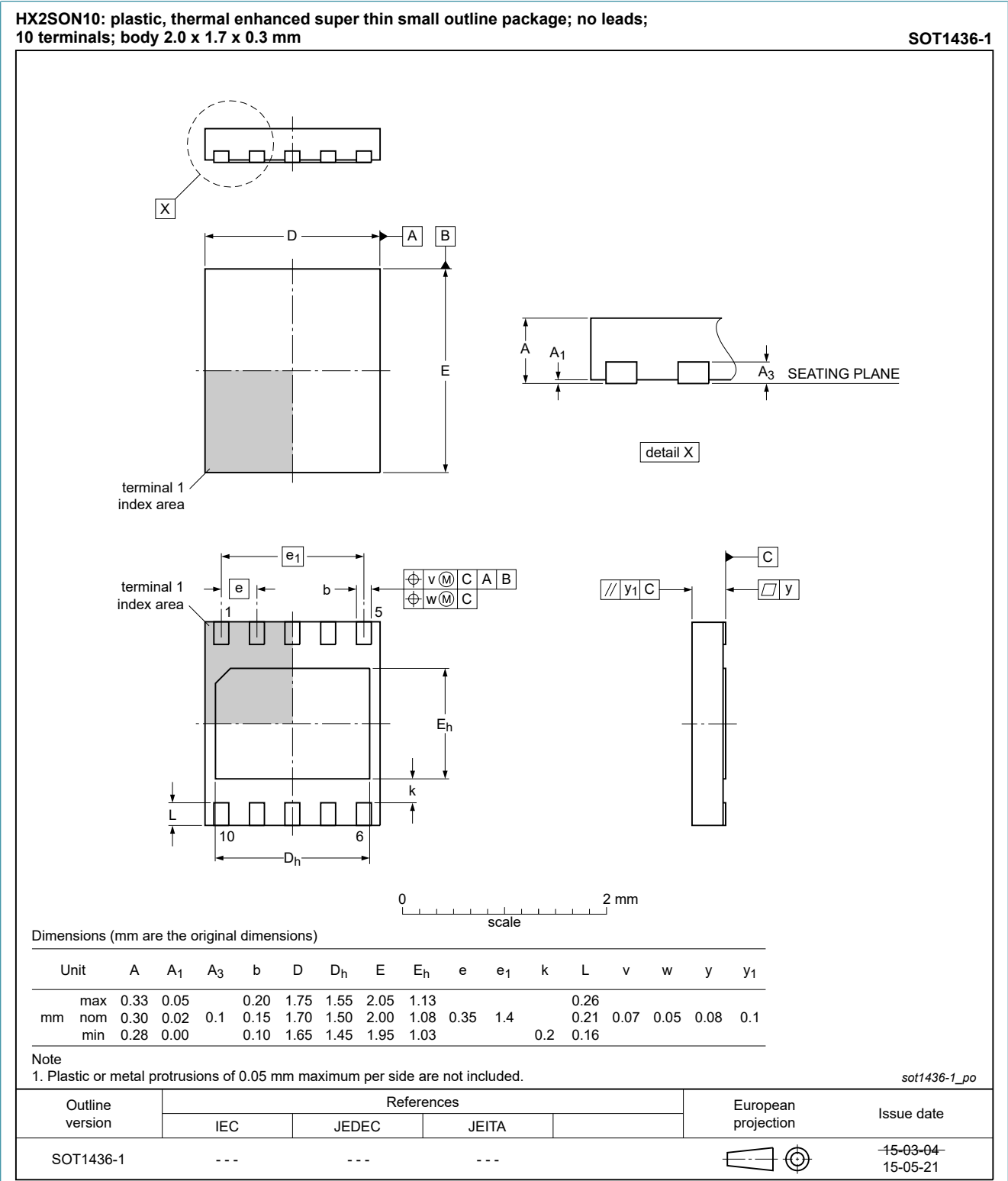


Fig. 1. Package outline HX2SON10 (SOT1436-1)

3. Soldering

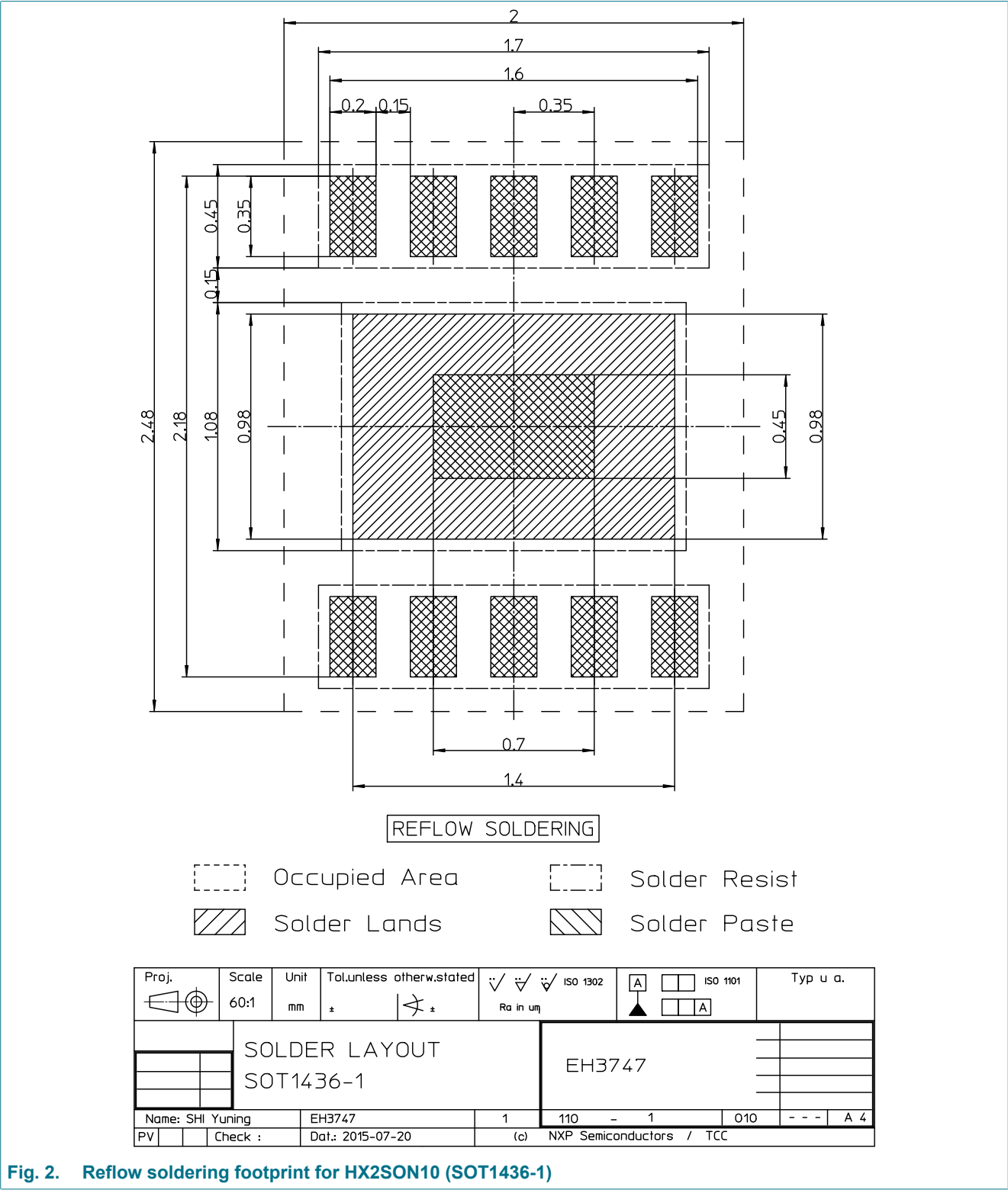


Fig. 2. Reflow soldering footprint for HX2SON10 (SOT1436-1)

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4. Legal information

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